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PTO/SB/33 (07/05)

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PRE-APPEAL BRIEF REQUEST FOR REVIEW		Docket Number (Optional)	
		ITL.1105US (P18745)	
I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to "Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450" [37 CFR	Application Number		Filed
	10/814,528		March 31, 2004
on March 26, 2007	First Named Inventor		
Signature //www.march 26, 2007	Tom E. Pearson		
· · · · · · · · · · · · · · · · · · ·	Art Unit E		Examiner
Typed or printed name Nancy Meshkoff	2833		Vanessa Mary Girardi
Applicant requests review of the final rejection in the above-identified application. No amendments are being filed with this request.			
and requeet.			
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This request is being filed with a notice of appeal.			
The review is requested for the reason(s) stated on the attached sheet(s).			
Note: No more than five (5) pages may be provided.			
I am the		~ ~	_
applicant/inventor.			
Signature Signature			
assignee of record of the entire interest.  See 37 CFR 3.71. Statement under 37 CFR 3.73(b) is enclosed.  Timothy N. Trop			
(Form PTO/SB/96) Typed or printed			
attorney or agent of record.  Registration number	(713) 468-8880		
		Telep	hone number
attorney or agent acting under 37 CFR 1.34.			
Registration number if acting under 37 CFR 1.34	-	March 26, 2007  Date	
NOTE: Signatures of all the inventors or assignage of record of the or	atira intorost or	their represents	utive/s) are required
NOTE: Signatures of all the inventors or assignees of record of the entire interest or their representative(s) are required. Submit multiple forms if more than one signature is required, see below*.			

This collection of information is required by 35 U.S.C. 132. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.11, 1.14 and 41.6. This collection is estimated to take 12 minutes to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Tradeamrk Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS. SEND TO: Mail Stop AF, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

\_ forms are submitted.

\*Total of

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THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re Applicant:

Tom E. Pearson et al.

Serial No.: 10/814,528

Filed: March 31, 2004

For: Infrared Transmissive Integrated

Circuit Socket Cap

Art Unit: 2833

Examiner: Vanessa Mary Girardi

Docket: ITL.1105US

P18745

Assignee: Intel Corporation

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## STATEMENT IN SUPPORT OF PRE-APPEAL BRIEF REQUEST FOR REVIEW

Sir:

Claim 1 calls for an infrared transmissive cap removably secured to a hinged cover on a socket housing. The cap may protect the socket part of the integrated circuit insulation while facilitating surface mounting of the socket to the printed circuit board. Infrared radiation from the surface mount oven passes through the cap to heat the socket (rather than the cap) so that the socket is thereby soldered to the printed circuit board.

The cited reference to Liao, if anything, teaches away. It simply relates to a cap for a socket. The problem with Liao is that the cap becomes heated in the usual course. Thus, if anything, Liao teaches away from the claimed invention and presents an example of the problem solved by the present application.

The cited reference to Ciambrone has nothing to do with an integrated circuit socket. It is a soldering tool, not a socket. The fact that infrared transmissive elements have been used in the

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Nancy Meshkoff

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paşt is not sufficient to show that it would be obvious to use an infrared transmissive cap in place of the cap used by Liao. Certainly, this was not obvious to Liao.

The suggestion that the reason to substitute the infrared soldering tool of Ciambrone for the non-infrared transmissive cap of Liao is that the cap may be recycled, reformed, and reused is noted, but makes no sense. Liao would respond that this rational provided him no reason to go to the trouble to use an infrared transmissive cap because his current cap can be recycled, reformed, and reused. In short, nothing in either Liao or Ciambrone teaches any reason to use infrared transmissive material for the cap of Liao. Suggestions to the contrary rely on nothing but hindsight reasoning.

For all these reasons, the cited references provide no guidance to one skilled in the art, such as Liao, as to why Liao's solution could be improved. There is not even a recognition that the cover of Liao would heat up in the course of reflow. Not only do the references fail to teach the solution claimed here, but they do not even recognize the problem that gives rise to the claimed solution.

For all these reasons, reconsideration would be appropriate.

Respectfully submitted,

Date: March 26, 2007

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